



IT-958G

CCL : IT-958GTC
Prepreg: IT-958GBS

High Tg / Halogen Free / Low Loss Laminate & Prepreg

- ANSI Type : **No ANSI**
- Applicable IPC-4101 /127/128/130 ; IPC-4103 /240/540
- Advanced High Tg Resin Technology
- Excellent electrical performance
- Lower Dk (3.70 @ 10GHz) and low Df (0.0070 @ 10GHz)
- Stable Dk/Df with different environment

Laminate properties

Items	IPC TM-650	Typical Value	Unit
Peel Strength, minimum A. Low profile copper foil	2.4.8	3.5~4.2	lb/inch
Volume Resistivity	2.5.17.1	1x10 ¹⁰	MΩ-cm
Surface Resistivity	2.5.17.1	1x10 ¹⁰	MΩ
Moisture Absorption, maximum	2.6.2.1	0.08	%
Permittivity (Dk, 50% resin content)			--
A. 1GHz	2.5.5.9	3.85	
B. 2GHz	2.5.5.13	3.80	
C. 5GHz	2.5.5.13	3.74	
D. 10GHz	2.5.5.13	3.70	
Loss Tangent (Df, 50% resin content)			--
A. 1GHz	2.5.5.9	0.0054	
B. 2GHz	2.5.5.13	0.0057	
C. 5GHz	2.5.5.13	0.0062	
D. 10GHz	2.5.5.13	0.0070	
Flexural Strength, minimum			
A. Length direction	2.4.4	480-510	N/mm ²
B. Cross direction		400-430	
Thermal Stress 10 s at 288°C			
A. Unetched	2.4.13.1	Pass	Rating
B. Etched		Pass	
Flammability	UL94	V-0	Rating
Comparative Tracking Index (CTI)	ASTM D3638 / UL 746	CTI 2(250-399)	Class (Volts)
Maximum Operating Temperature(MOT)	UL 746	130	°C
Glass Transition Temperature(DSC)	2.4.25	175	°C
Decomposition Temperature(5% W.L)	2.4.24.6	400	°C
X/Y Axis CTE (40°C to 125°C)	2.4.41	12/14	ppm/°C
Z-Axis CTE			
A. Alpha 1		40	ppm/°C
B. Alpha 2	2.4.24	230	ppm/°C
C. 50 to 260 Degrees C		2.5	%
Thermal Resistance			
A. T260	2.4.24.1	>60	Minutes
B. T288		>60	Minutes